

AMENDMENTS TO THE SPECIFICATION

Please replace the Abstract of the disclosure section, located immediately following the Claims, with the following replacement Abstract:

~~An object is to provide a molded product, which has dielectric properties that the conventional liquid crystal polyester resin has not realized, and simultaneously which keeps a heat resistance such as solder reflow of a liquid crystal polyester, and which is used in information and telecommunications equipment employed in high frequency band regions such as microwaves and millimeter waves. A molded product of a wholly aromatic liquid crystal polyester resin composition which has having a dielectric constant of 3.0 or less and a dielectric dissipation factor of 0.04 or less and ~~which is~~ obtained by an injection molding of a composition comprising 90 to 45 percent by weight of the wholly aromatic liquid crystal polyester having a melting point of 320C or more, 10 to 40 percent by weight of an inorganic spherical hollow material having an aspect ratio of 2 or less, and 0 to 15 percent by weight (100 percent by weight in total) of an inorganic filler~~

having an aspect ratio of 4 or more. The molded product ~~of the present invention has~~ dielectric properties suitable for information and telecommunications equipment, and is excellent in solder heat resistance, processability, and dimensional stability. ~~so that~~ The molded product is advantageous as a substrate material for use in information and telecommunications equipment such as a cellular mobile phone and as a fixing/holding ~~or a holding~~ member of a transmitter-receiver element.

Please replace Table 2 at page 20, line 1 with the following
 replacement Table 2, marked-up to show changes relative to the
 original:

Table 2

	Specific Gravity of Resin Composition	Fracture Rate $\frac{X}{Y}$	Fractured Micro Hollow Body (E) (wt%)	(D+E)/C	Relative Dielectric Constant	Dielectric Dissipation Factor	Soldering Heat Resistance (°C)	Surface Property of Product	Flowability Evaluation
Example 1	1.11	<u>0.048</u>	4 <u>1.0</u>	0.040.05	2.73	0.026	330	o	o
Example 2	1.01	<u>0.045</u>	1 <u>1.4</u>	0.05	2.64	0.023	325	o	o
Example 3	1.20	<u>0.085</u>	1 <u>1.3</u>	0.440.42	2.91	0.030	330	o	o
Example 4	1.04	<u>0.094</u>	3 <u>2.0</u>	0.360.34	2.85	0.026	330	o	o
Example 5	1.04	<u>0.088</u>	2 <u>2.8</u>	0.370.34	2.86	0.027	320	o	o
Example 6	1.07	<u>0.090</u>	3.6	0.100.09	2.84	0.023	320	o	o
Com- parative Example 1	1.06	<u>0.0456</u>	27 <u>27.4</u>	0.220.46	3.11	0.022	330	x	x
Com- parative Example 2	1.38	—	—	—	3.02	0.035	300	x	o
Com- parative Example 3	1.24	<u>0.0460</u>	10 <u>51.8</u>	0.540.36	3.12	0.031	330	o	o
Com- parative Example 4	1.02	<u>0.071</u>	2 <u>2.1</u>	0.090.07	2.68	0.025	300 or less	o	o
Com- parative Example 5	1.60	—	—	—	3.61	0.033	340	o	o
Com- parative Example 6	1.62	—	—	—	3.65	0.034	330	o	o